

Resistive Memory for Neuromorphic Algorithm Acceleration

NICE Workshop

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Outline

- Motivation
- Neural Core Design and Architecture
- Resistive Memory Device Assessment
- Summary and Future Work





Brain Inspired Computing at Sandia

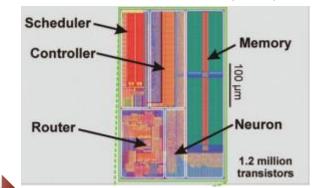
- Sandia established a multidisciplinary LDRD project in neuromorphic computing project in October 2015
 - Hardware Acceleration of Adaptive Neural Algorithms (HAANA)
 - Algorithms research
 - Hardware and Device Architectures
 - Resistive Memory Devices
- Some of the initial work on learning architecture and resistive devices covered in this talk





Neural-inspired Computing Hardware

DARPA, IBM TrueNorth (2014):

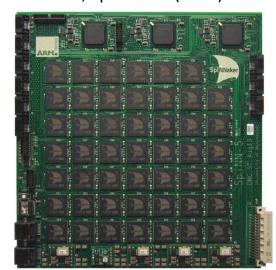


Mark I Perceptron (Rosenblatt 1960):



Arvin Calspan Advanced Technology Center; Hecht-Nielsen, R. *Neurocomputing* (Reading, Mass.: Addison-Wesley, 1990); Cornell Library;

EU HBP, SpiNNaker (2014):









Current State of the Art in Neural Algorithm Computing

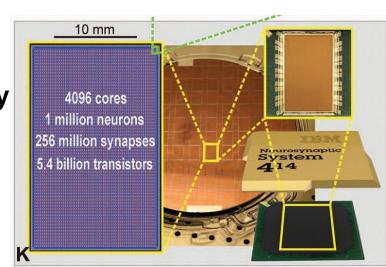
CPU/GPU

- Most general; common programming languages
- Lowest power efficiency and performance
- Memory separate from chip
- Example: Google deep learning study (CPU→GPU)

FPGA

- General; requires hardware design language
- Moderate performance and efficiency
- Custom IC (Truenorth, Spinnaker)
 - Specific: ex. executes STDP
 - Highest performance and efficiency
 - Expensive, 40MB local memory
 - Example: IBM Truenorth
- Moore law has provided enormous benefits to all of these technologies



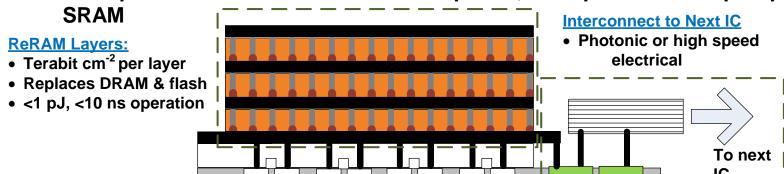




Next Generation of Neural Algorithm Computing

- Problem: neural algorithm training requires significant memory and logic interaction
- What is the most efficient way to combine memory, logic and interconnects?
- SRAM: on chip cache memory is limited to ~40MB digital (Intel E7)
 - ns latency, max regardless of CPU, GPU or ASIC
- Off chip communication to DRAM costs >100 pJ/op, ~10ns latency
- Resistive memory on chip: can be stacked to >TB/cm², >100 layers
 - On chip access, <pJ per op and <1ns latency possible
 - Terabit densities on single chip on chip wiring is low energy!
 - Sub 1V switching minimal CV²f loss (DRAM 2-5V)
- Significant power savings using a ReRAM based HW accelerator

- Example: Taha found 16x reduction in power, 6x improvement in perf per chip over



High Performance Logic



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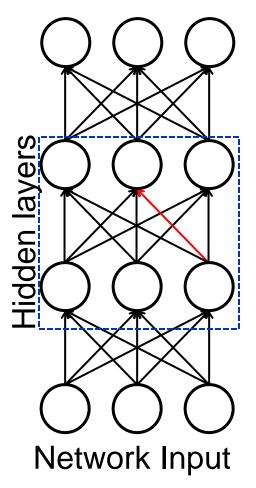
Backpropagation of Errors

- Straw-man algorithm others can be used
- Initial linear network training did not have a method of training hidden layers
- Backpropagation of errors gave a method to train hidden network layers

How does backpropagation work?

- 1. Forward calculation of output
- 2. Calculate all weight deltas and compute error derivative (backprop errors)
- 3. Combine this with learning rate to update weight

Network Output

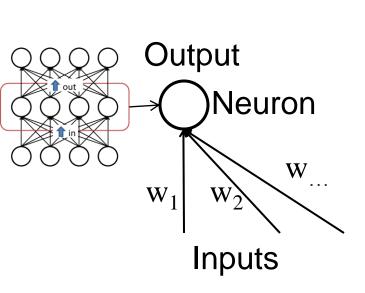


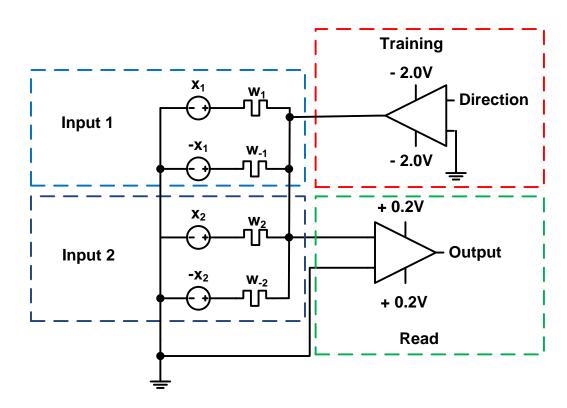




Mapping weight matrix to ReRAM

Single ReRAM based neuron

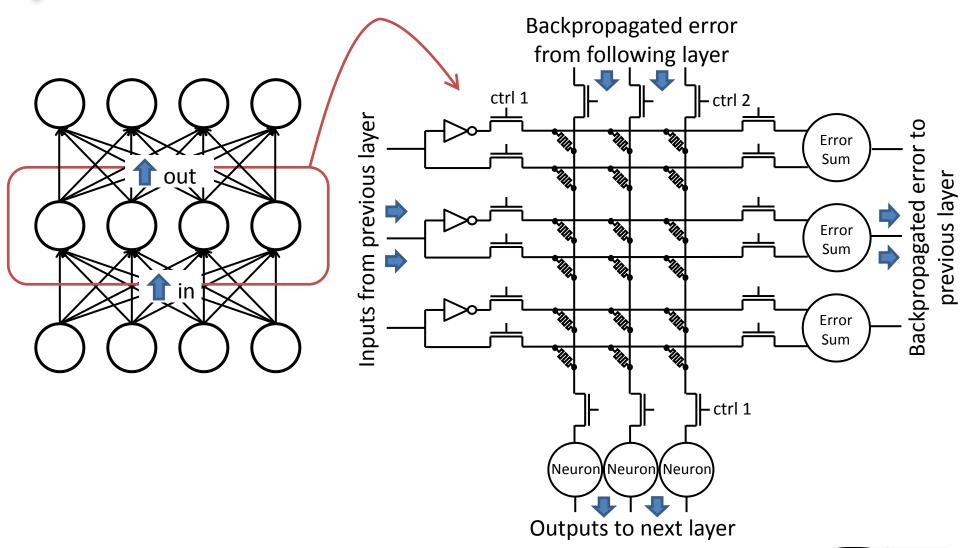








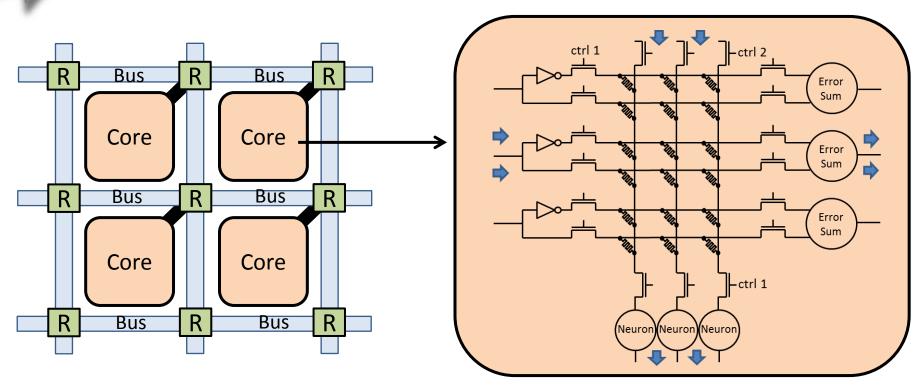
Backpropagation Circuit







System Level Architecture



Neuromorphic core:

- Stores and updates weights
- Computes weighted sum of inputs
- Computes error derivatives
- Applies non-linear neuron function

Inputs:

- Previous layers' neuron outputs
- Following layers' error derivatives
- Control signals

Outputs:

- Neuron outputs to following layer
- Error derivatives to prev. layer





Inter-Core Connectivity Options

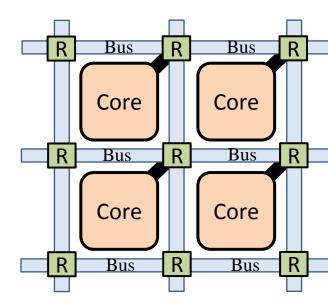
Must consider options for interconnecting multiple neural cores:

Maximize Flexibility:

- All neuron inputs/outputs go off chip, training signals come in
- Least energy efficient, most complex wiring Maximize Energy Efficiency:
- Connections hardwired, perhaps some flexibility through FPGA architecture
- Least flexible design
- Each core independently does learning based on local inputs and outputs

Hybrid Approach Also Possible

Use local buses with some off-chip capability

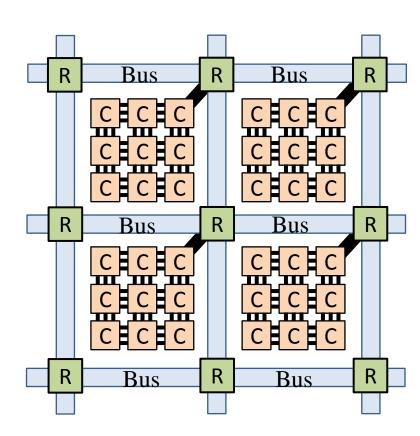






Configuring Crossbars

- The size of a single ReRAM crossbar will be limited by analog signal to noise ratio and interconnect line resistance and max current considerations
- Weights in a network will most likely not correspond to the number of weights in one crossbar
- Solution: multiple crossbars per core
 - Analog signal enhancement between separate cores
- Maximize efficiency:
 - Share a single A/D converter between cores in different layers
 - Use digital communications for long distance communications







Outline

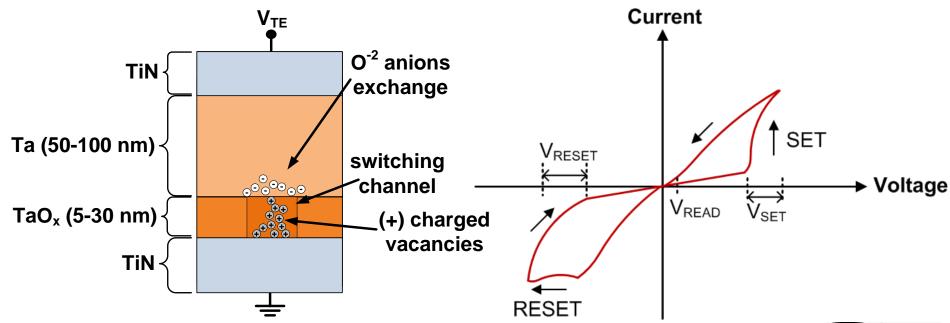
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Oxide-Based Resistive Memory

- "Hysteresis loop" is simple method to visualize operation
 - (real operation through positive and negative pulses)
- Resistance Change Effect (polarities depend on device):
 - Positive voltage/electric field: low R O⁻² anions leave oxide
 - Negative voltage/electric field: <u>high R</u> O⁻² anions return
- Common switching materials: TaO_x, HfO_x, TiO₂, ZnO





Typical Device Fabrication

Top Aluminum

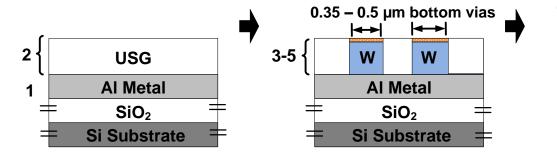
Bit

USG

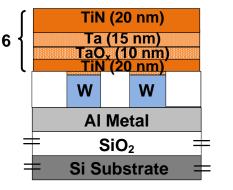
Via

- 1. Deposit Bottom Metal (AI)
- 2. Deposit USG

- 3. Etch via holes in USG
- 4. Deposit W and TiN layers
- 5. CMP

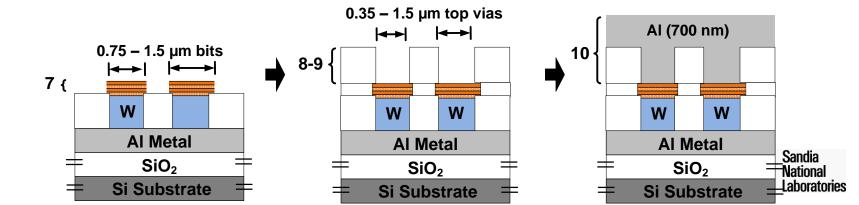


6. Deposit bit stack (layers enlarged for clarity)



7. Etch bits

- 8. Deposit top USG
- 9. Etch top via holes in USG
- 10. Deposit top Al



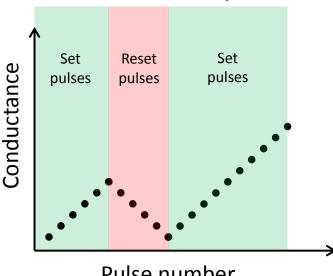


ReRAM Requirements for a **Neural Accelerator**

Different requirements than standard memory:

- Linear dynamic response
 - Perhaps some flexibility with this
- Low variability
 - Device to device, cycle to cycle
 - Need correct average behavior
- Wide resistance range
- Low read noise
- Endurance: high
- Retention: weeks

Ideal RRAM Response



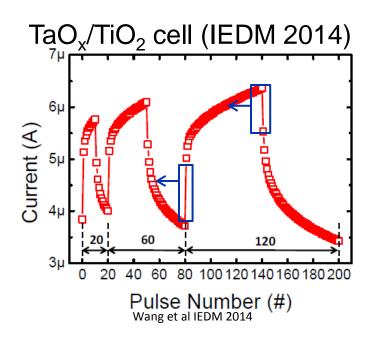




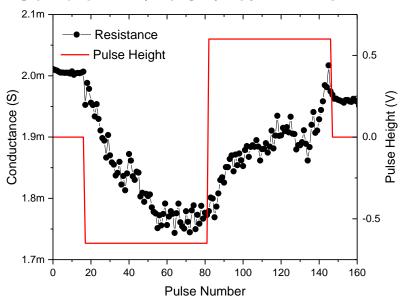


Weight Updates with ReRAM

- Square pulse train of fixed amplitude and duration (typ. µs)
- Most common method of characterizing
- Do not want to erase many pulses with opposing pulse



Sandia TiN/TaOx/Ta/TiN ReRAM



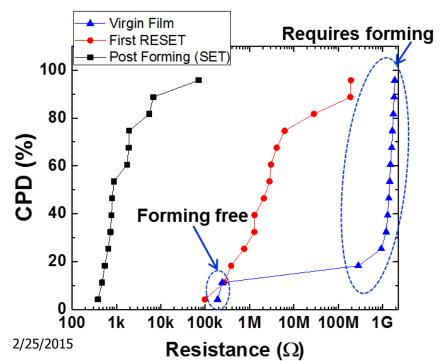


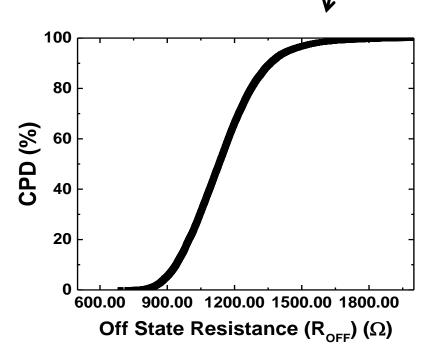


Cycle No.

Variability and Noise

- Interdevice variability: device to device, can be >10x
 - Variations in film thickness, topography
- Intradevice variability: cycle to cycle, can be >2x
 - Fundamental physical attributes
- Random telegraph noise:
 - Affects read current, usually least significant

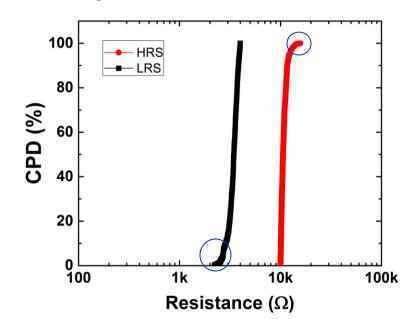


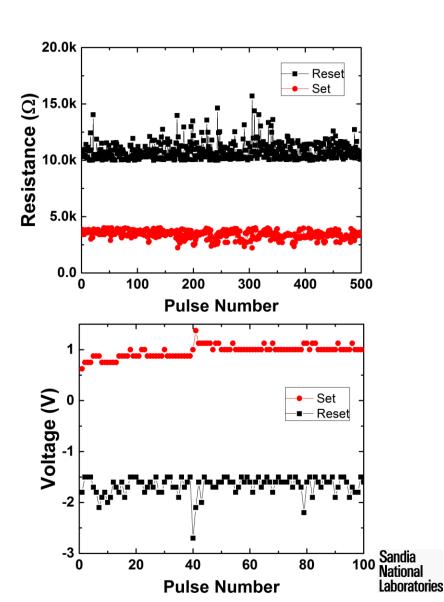




Closed Loop Cycling

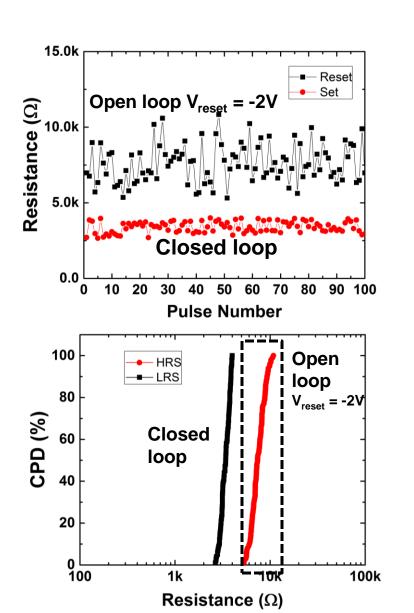
- Resistance "find" routine
 - 400 µs pulses
 - $-V_{\text{pulse}}$ =0.5 \rightarrow V_{R-target} (100 mV inc)
- End
 - R>R_{target} (off)
 - R<R_{target} (on)

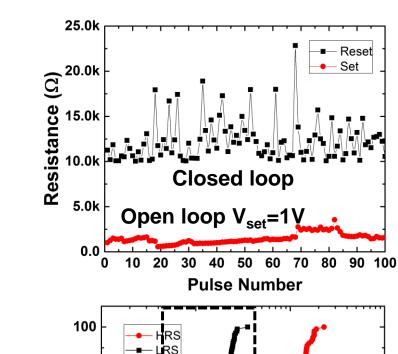


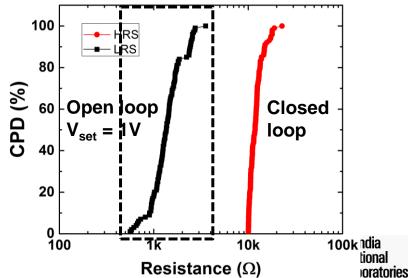




Open/Closed Loop Cycling



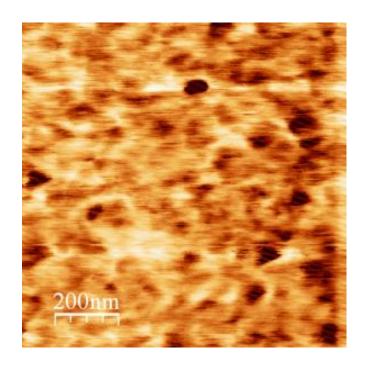


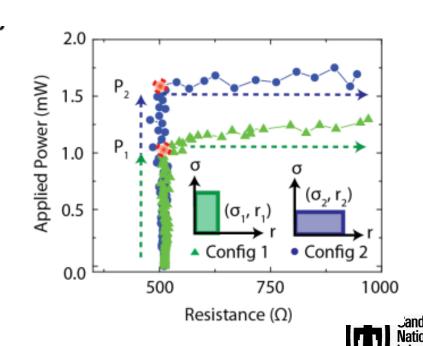




Where does noise originate from?

- Important question not yet a great answer
- Device to device: film thickness variations?
- Cycle to cycle: Internal state variations?

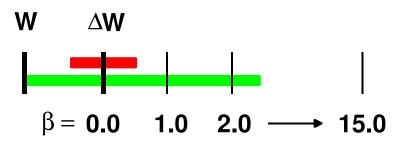






How much noise can be tolerated?

- First step: Simulation Study
 - Mimic on-line learning with incremental open-loop resistance nudges
 - Assume adjustment of each W by ∆W is done imprecisely
 - Add white noise to each weight update:

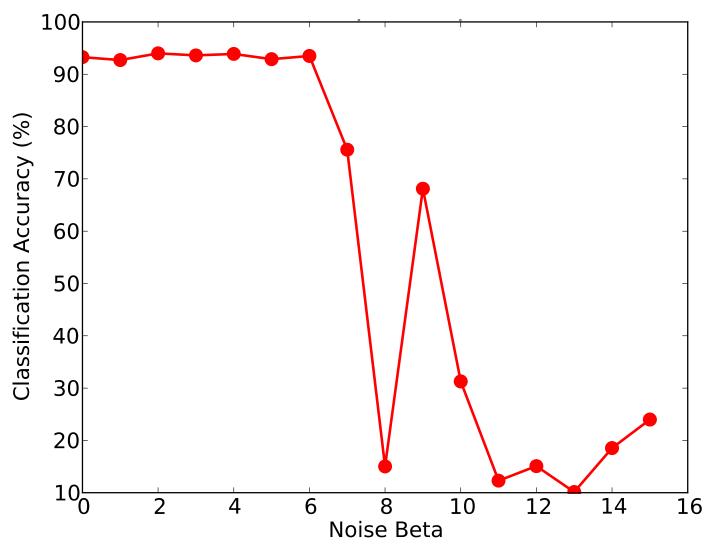


- Train on individual images or mini-batch or full epoch
- Train for fixed epoch count, or to convergence
- Adjust backprop step-size "α" if needed
- Classify as usual with final weights





Noise vs Accuracy (Fixed Iteration)







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Summary and Future Work

Summary

- Sandia has launched a new project which includes significant effort in accelerating neural algorithms
- ReRAM will allow TB of memory to be monolithically integrated circuit with high performance logic transistors
 - Saves expensive off-chip (DRAM) operations
 - Lower energy on-chip routing
 - Overcomes density limitations of digital SRAM

Next Steps

- Assess and model variability of ReRAM
- Use this data to create an accurate system model in Xyce
- Finalize system architecture
- Perform power and performance estimates of ReRAM over SRAM accelerator



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